SUNSTAR传感与控制 http://www.sensor-ic.com/ TEL:0755-83376549 FAX:0755-83376182E-MAIL: szss20@163.com



SM5108

Ultra-Small, Low-Cost, OEM Pressure Die

- For Extremely High-Volume Applications
- Ultra-Small, Low Cost OEM Pressure Die

# DESCRIPTION

The SM5108 is a extremely small (0.65 mm x 0.65 mm) silicon micromachined piezoresistive pressure sensing chip that has been optimized to provide the highest possible accuracy for a die of this size. This performance is achieved through careful resistor placement and mechanical configuration. The small die results in a significant cost saving when compared to larger sensor die. Over 24,000 die come on a 150 mm wafer.

This sensor is intended for high volume applications where cost is a critical factor, such as consumer tire pressure gauges or disposable pressure gauges. The SM5108 is available as an absolute pressure sensor in full-scale ranges of 15 PSI, 30 PSI, 60 PSI, and 150 PSI. It is designed to be mounted on ceramic or PC board substrates by high-volume OEM manufacturers.

Die are probed, diced, and visually inspected and shipped on tape in rings.

Minimum order quantities apply to this product.



## **FEATURES**

- Available in 15 PSI, 30 PSI, 60 PSI, and 150 PSI ranges
- Extremely Low Cost
- Small size (0.65 mm x 0.65 mm)
- Constant Current or Constant Voltage Drive
- High Millivolt Output

# **APPLICATIONS**

- Automotive Tire Pressure Monitoring
- Engine Control
- Barometric Sensing
- Pneumatic Gages
- Hand-held Meters
- Home Appliances

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### CHARACTERISTICS FOR SM5108 - SPECIFICATIONS

All parameters are measured at 5.000V supply at room temperature, unless otherwise specified.

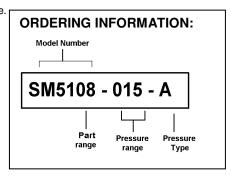
	Min.	Тур.	Max.	Units	Notes
Excitation Voltage	0	5.0	15	V	1
Excitation Current	0	1.5	2.5	mA	1
Span (FS Range)					5
15 PSI	65	100	135	mV	
30 PSI	65	100	135	mV	
60 PSI	65	100	135	mV	
150 PSI	100	150	200	mV	
Zero Offset	-35		35	mV	
TC Span	-24	-19	-15.5	%FS/100℃	3, 5
TC Offset	-7	-1	+7	%FS/100℃	3, 5
TC Resistance	+24	+27.5	+33	%/100℃	3, 5
Linearity	-0.2	-0.07	+0.2	%FS	4, 5
Bridge Impedance	4	5	6	kΩ	
Input Capacitance		<2		pF	5
Proof Pressure	3X			Rated FS	5
Burst Pressure	5X			Rated FS	5
Operating Temperature	-40		+125	∞	5
Storage Temperature	-40		+125	.€	5

#### Notes:

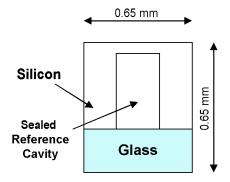
- Bridge may be driven with positive or negative excitation; positive output for positive pressure applied to circuit side
  of die when bridge is driven with positive voltage.
- 2. Measured from 0 to 70 ℃
- 3. Defined as best straight line.
- 4. Tested on a sample basis.

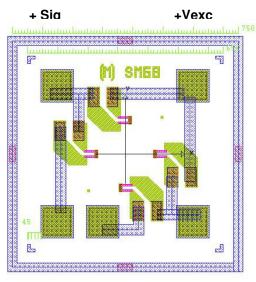
# **Pressure Ranges**

PSI	5108
15	015
30	030
60	060
150	150



A: Absolute (only)





- Vexc - Vexc - Sig

Top-View of SM5108 (0.65 mm square as sawn) Total thickness = 0.65 mm Covered under USA Mask-Copyright

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